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(12) **United States Design Patent**
Liu et al.

(10) **Patent No.:** **US D825,499 S**
(45) **Date of Patent:** **** Aug. 14, 2018**

(54) **LIGHT EMITTING DIODE PACKAGE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

Sep. 29, 2016 (TW) 105305761

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1

(Continued)

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Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — JCIPRNET

(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a first embodiment of the light emitting diode package showing our new design; FIG. 2 is a front view of the light emitting diode package of FIG. 1; FIG. 3 is a rear view of the light emitting diode package of FIG. 1; FIG. 4 is a left view of the light emitting diode package of FIG. 1; FIG. 5 is a right view of the light emitting diode package of FIG. 1; FIG. 6 is a top view of the light emitting diode package of FIG. 1; FIG. 7 is a bottom view of the light emitting diode package of FIG. 1; FIG. 8 is a perspective view of a second embodiment of the light emitting diode package showing our new design; FIG. 9 is a front view of the light emitting diode package of FIG. 8; FIG. 10 is a rear view of the light emitting diode package of FIG. 8; FIG. 11 is a left view of the light emitting diode package of FIG. 8; FIG. 12 is a right view of the light emitting diode package of FIG. 8; FIG. 13 is a top view of the light emitting diode package of FIG. 8; FIG. 14 is a bottom view of the light emitting diode package of FIG. 8; FIG. 15 is a perspective view of a third embodiment of the light emitting diode package showing our new design; FIG. 16 is a front view of the light emitting diode package of FIG. 15; FIG. 17 is a rear view of the light emitting diode package of FIG. 15;

(Continued)

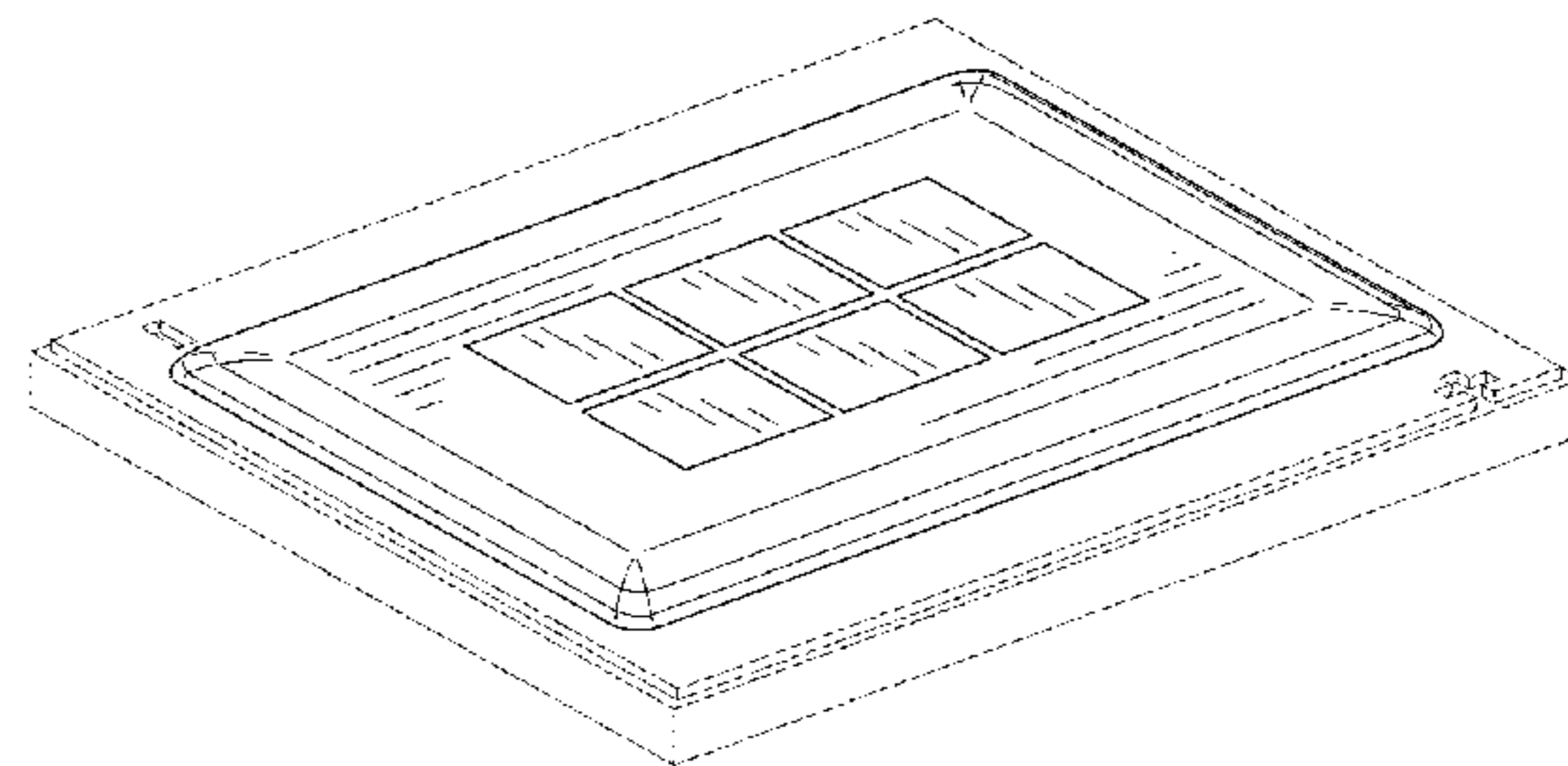
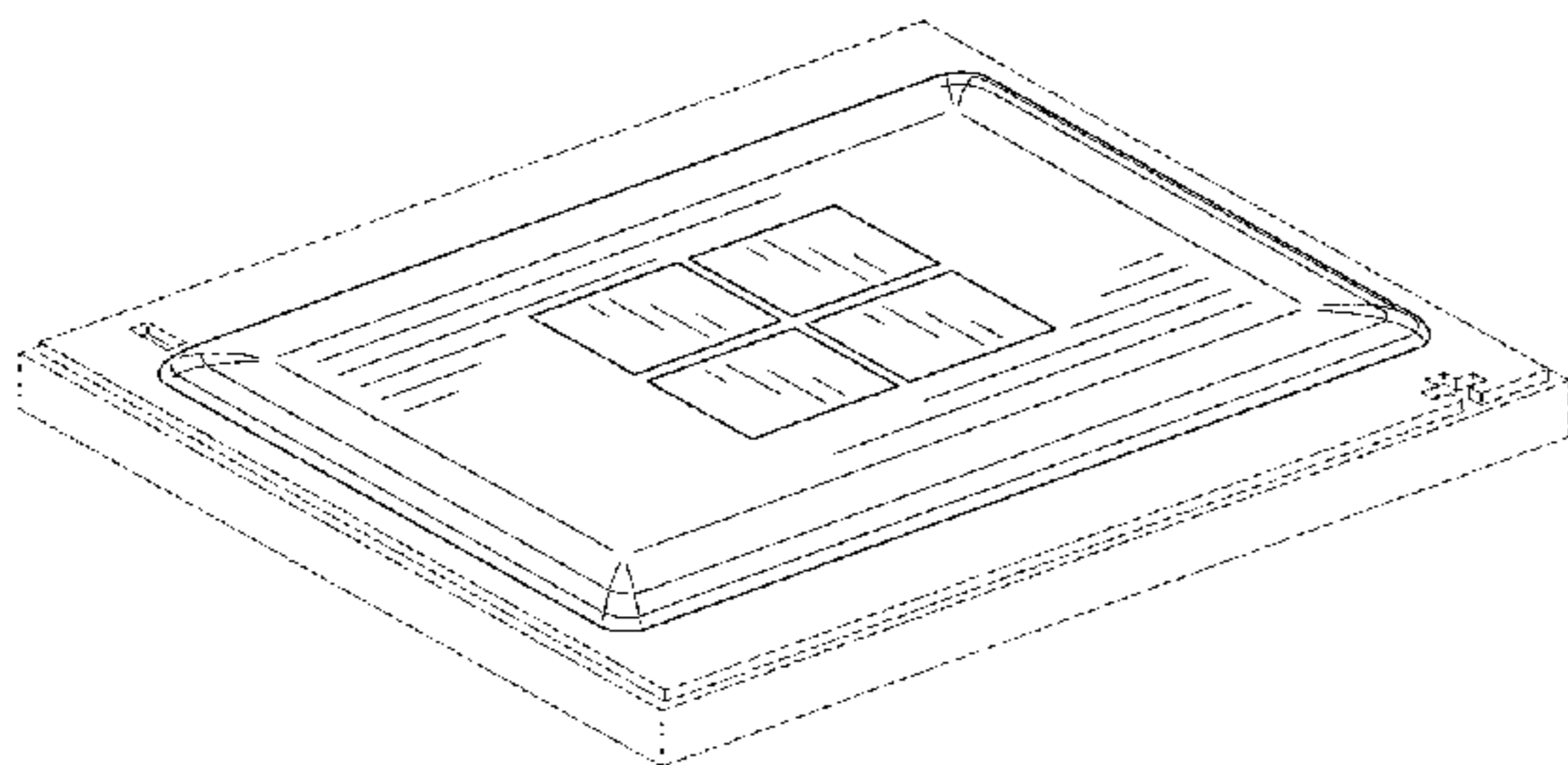


FIG. 18 is a left view of the light emitting diode package of FIG. 15;
 FIG. 19 is a right view of the light emitting diode package of FIG. 15;
 FIG. 20 is a top view of the light emitting diode package of FIG. 15; and,
 FIG. 21 is a bottom view of the light emitting diode package of FIG. 15.
 The broken lines in the drawings are included for the purpose of illustration and form no part of the claimed design.

1 Claim, 15 Drawing Sheets

(58) **Field of Classification Search**

CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
 H01L 27/156; H01L 31/02; H01L 33/00;
 H01L 33/04; H01L 33/08; H01L 33/10;
 H01L 33/20; H01L 33/38; H01L 33/42;
 H01L 33/48; H01L 33/62; H01L 33/483;
 H01L 33/486; F21K 9/00; F21K 9/30;
 F21K 9/54

See application file for complete search history.

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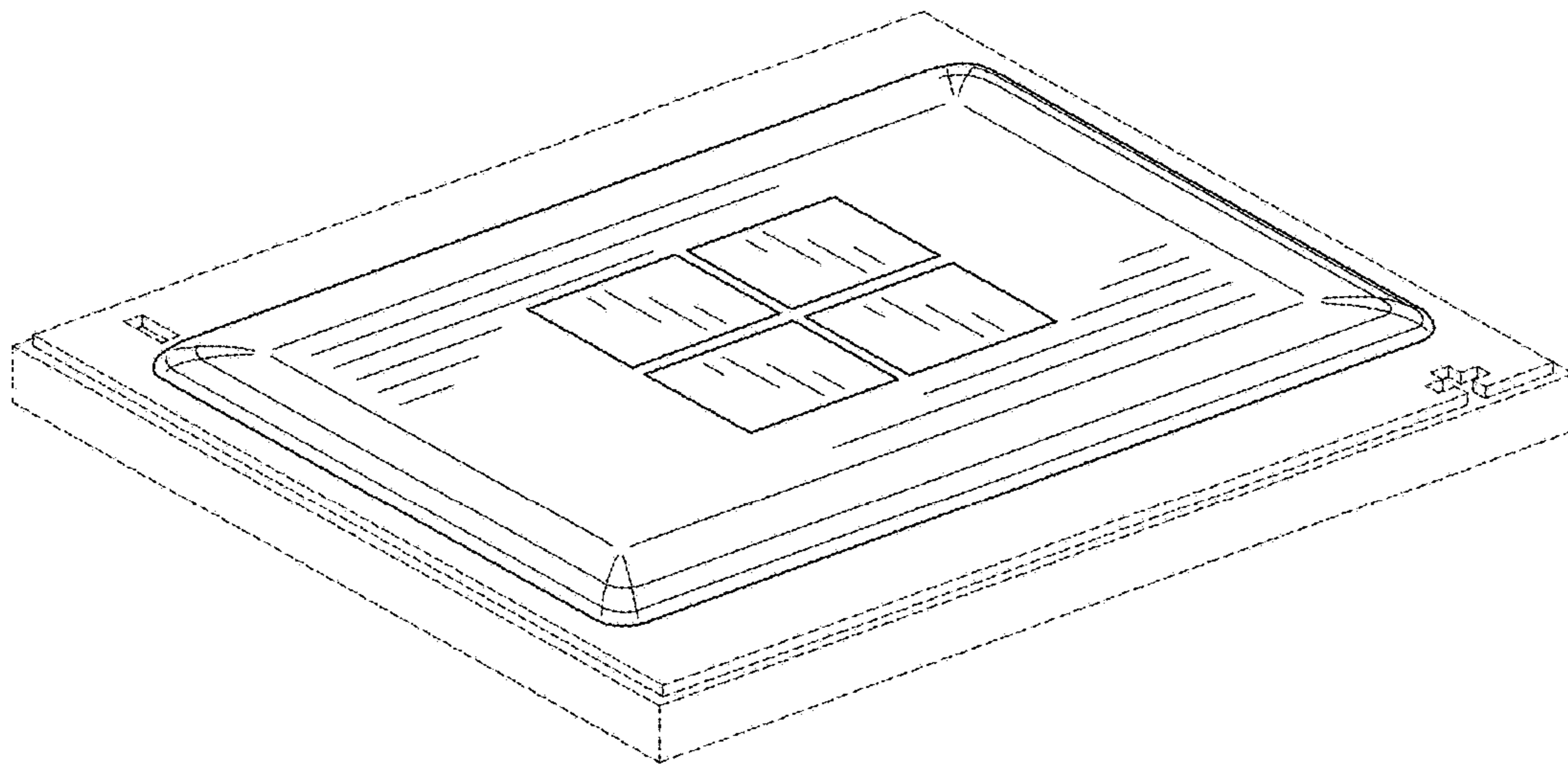


FIG. 1

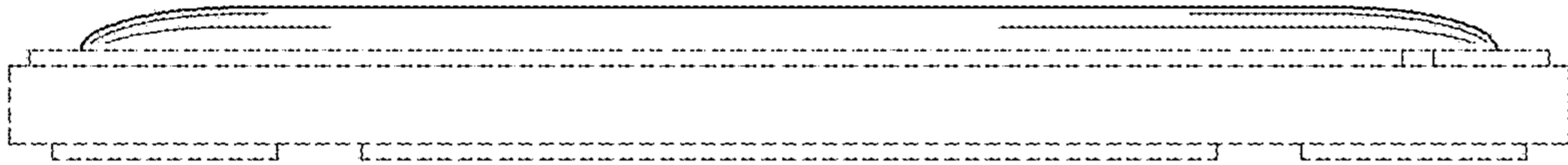


FIG. 2

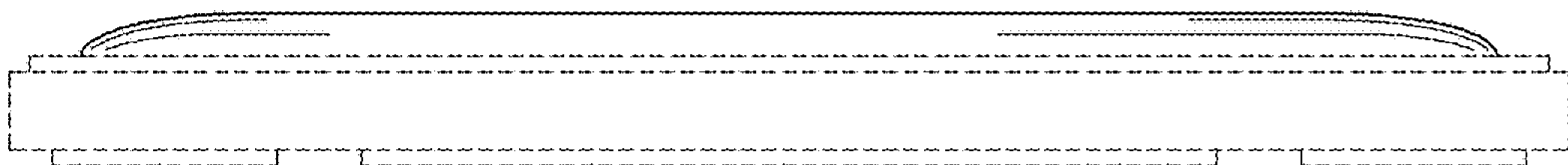


FIG. 3

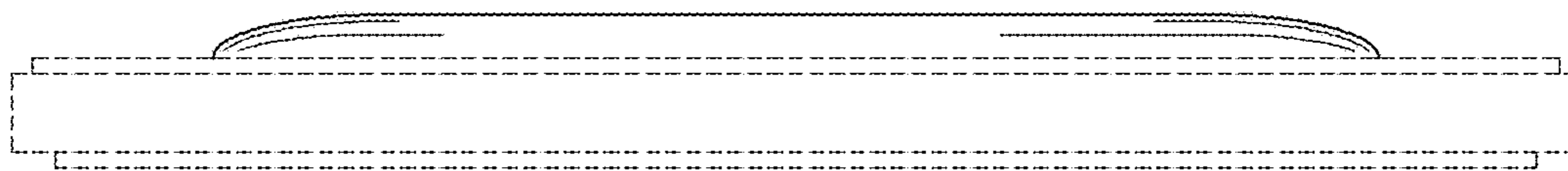


FIG. 4

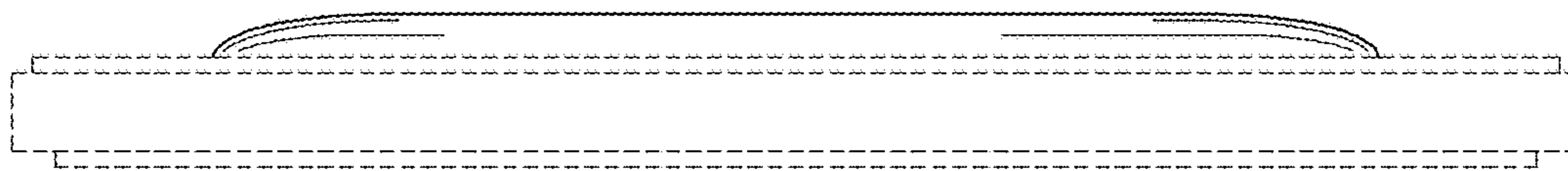


FIG. 5

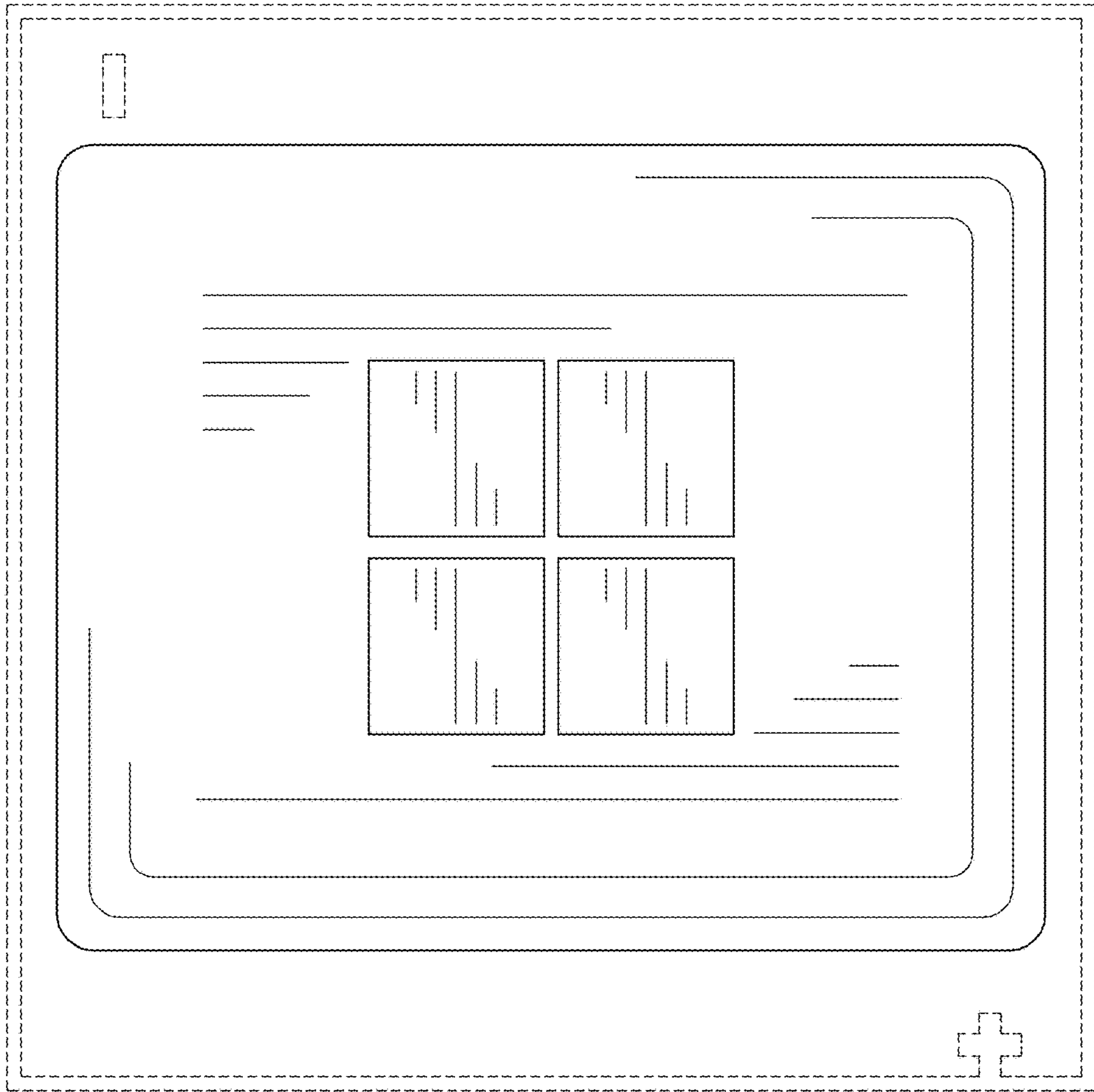


FIG. 6

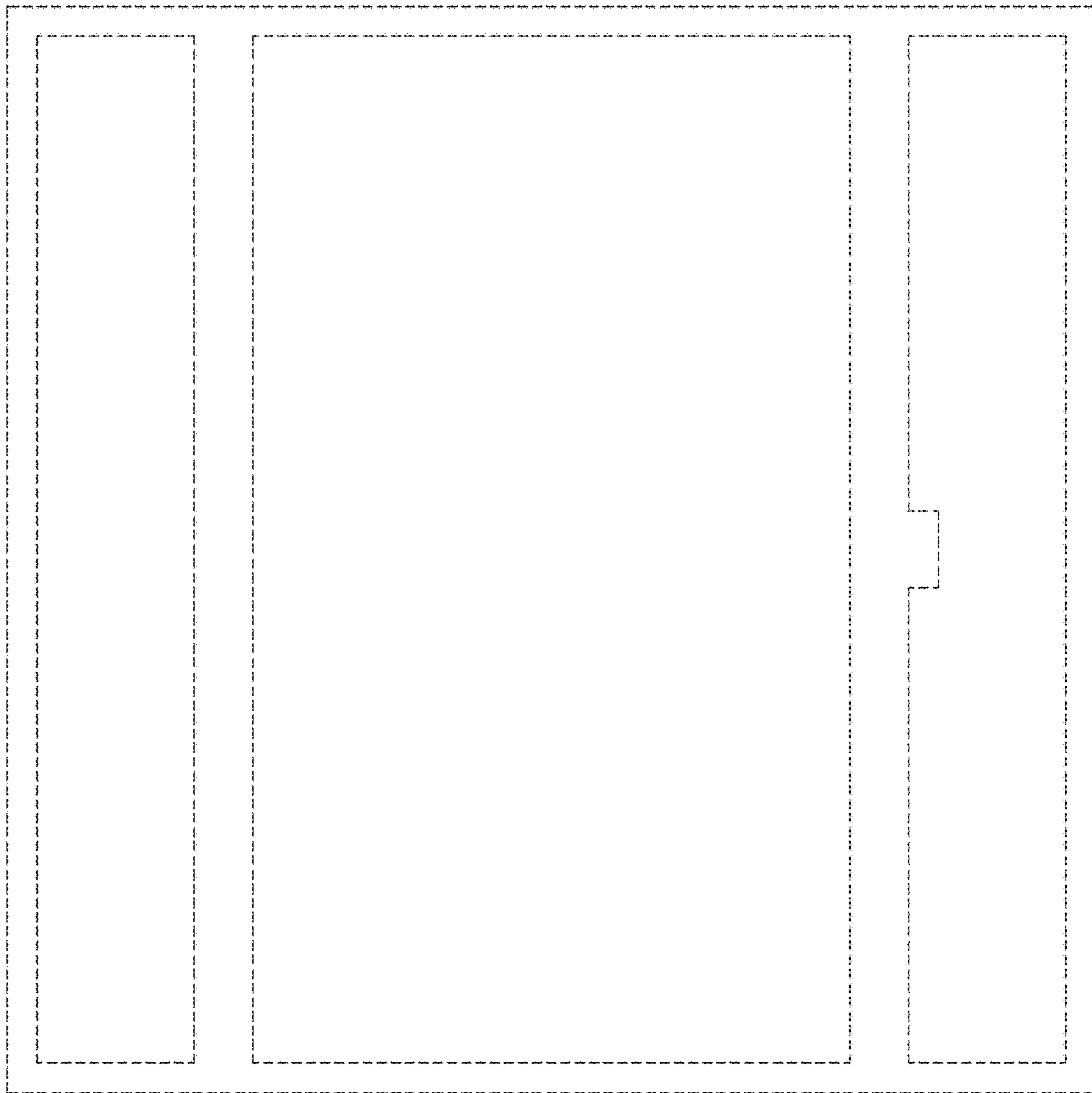


FIG. 7

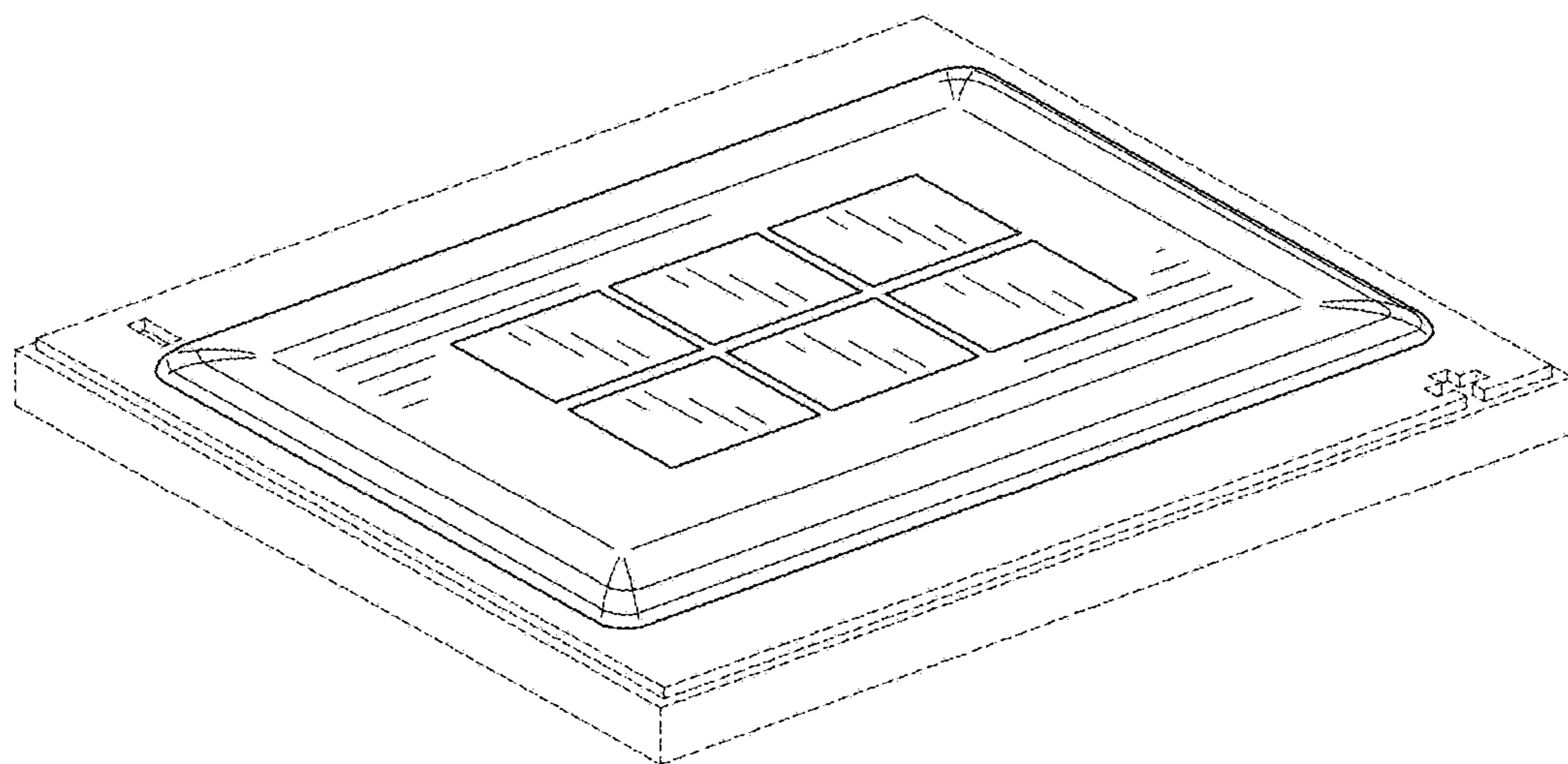


FIG. 8

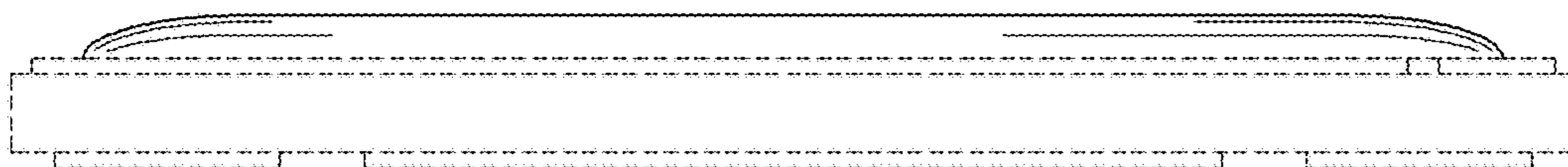


FIG. 9



FIG. 10

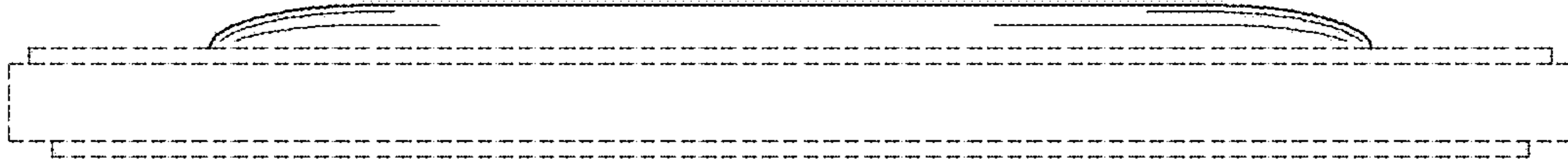


FIG. 11

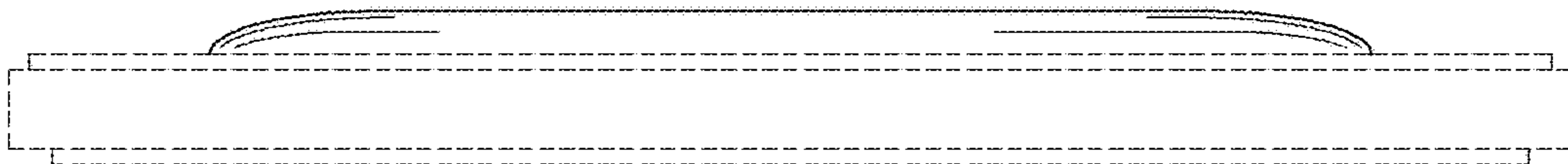


FIG. 12

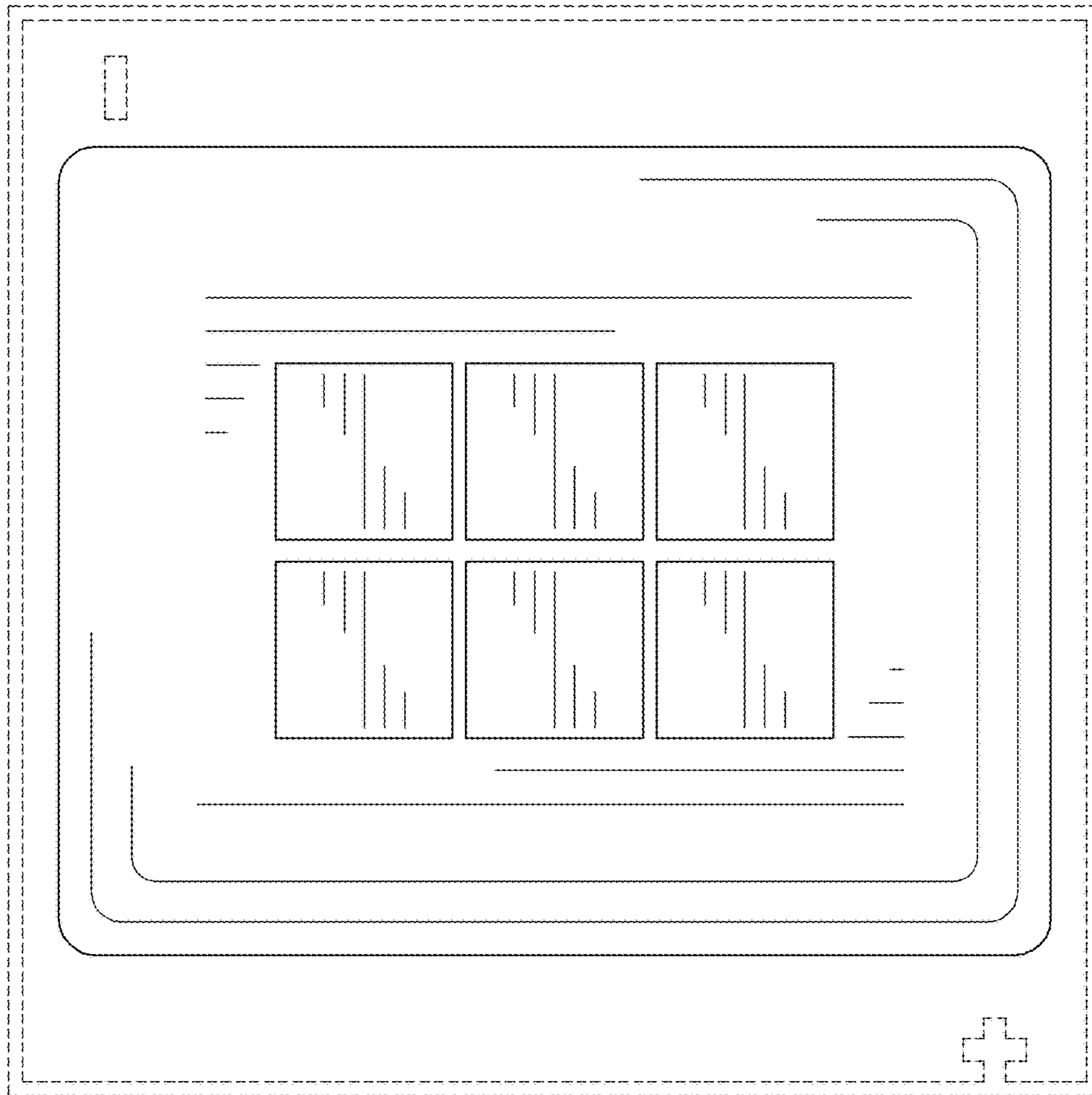


FIG. 13

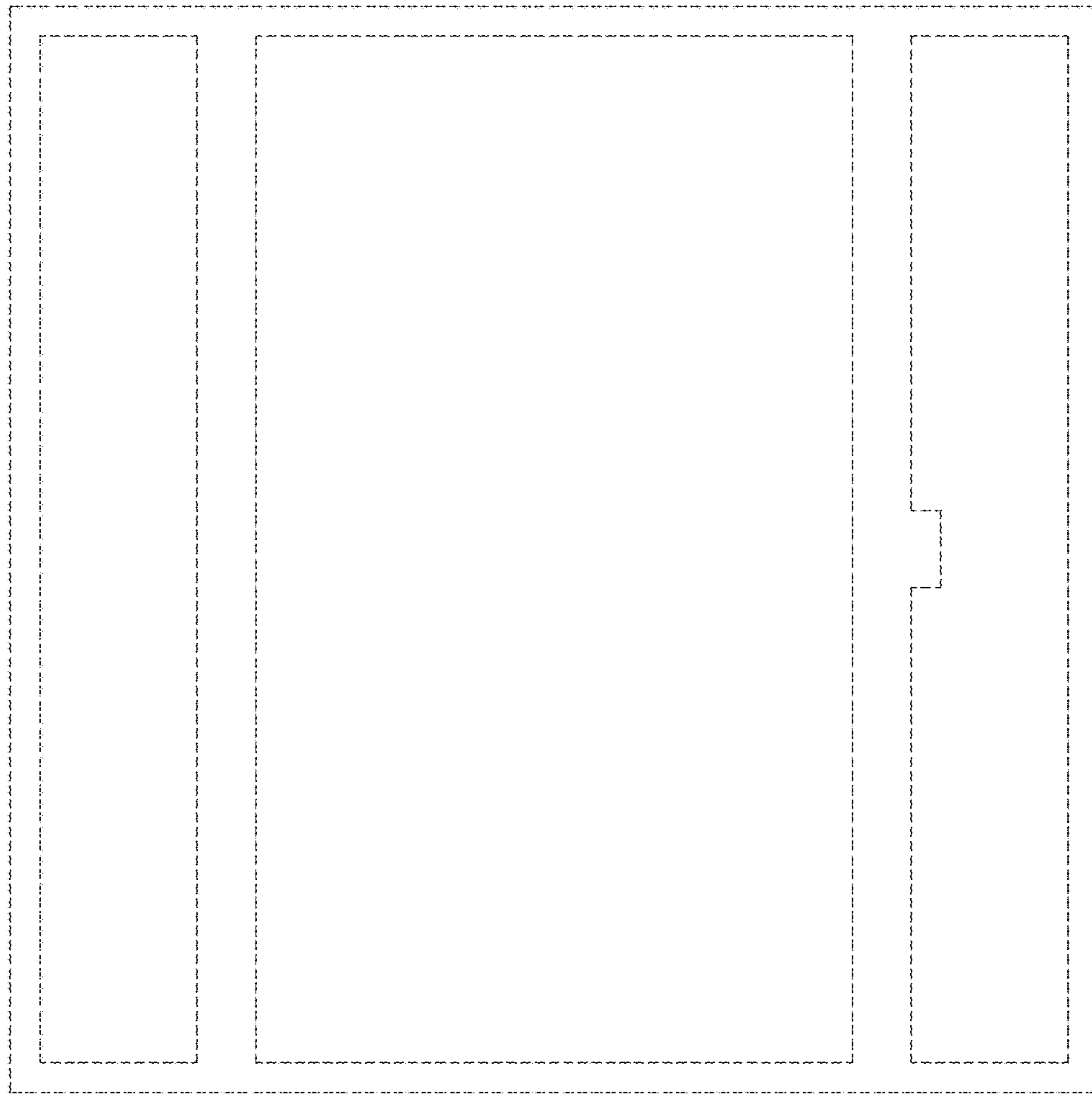


FIG. 14

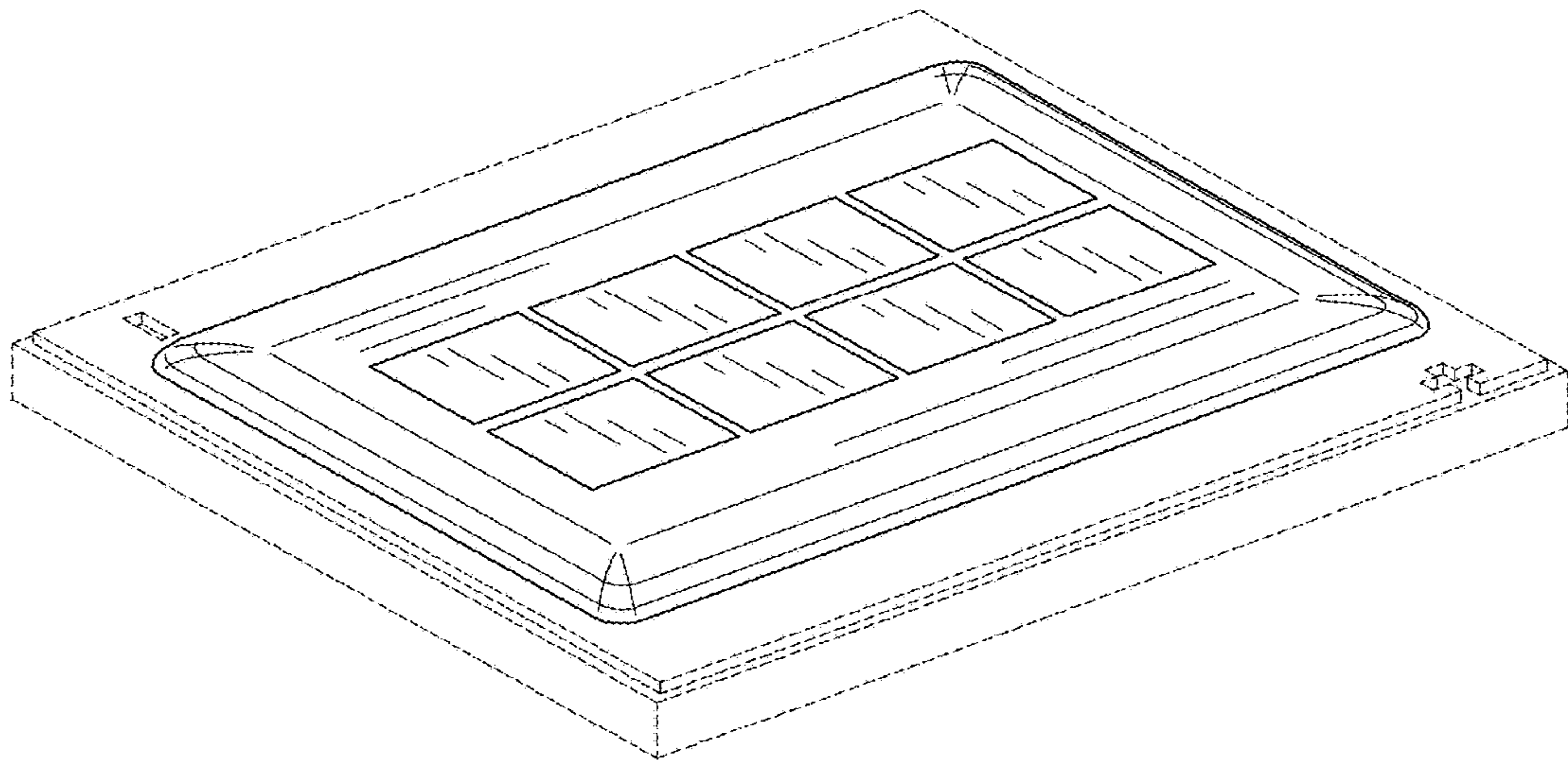


FIG. 15

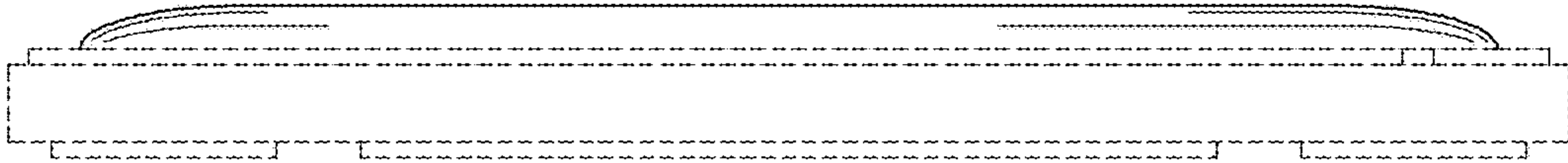


FIG. 16

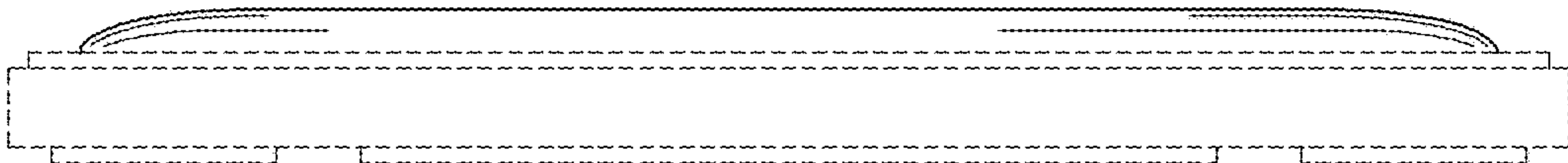


FIG. 17

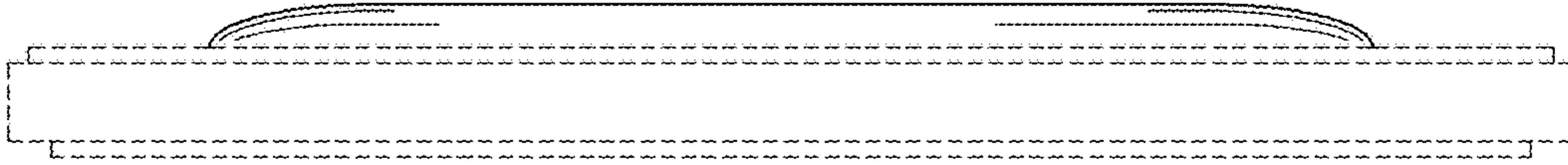


FIG. 18

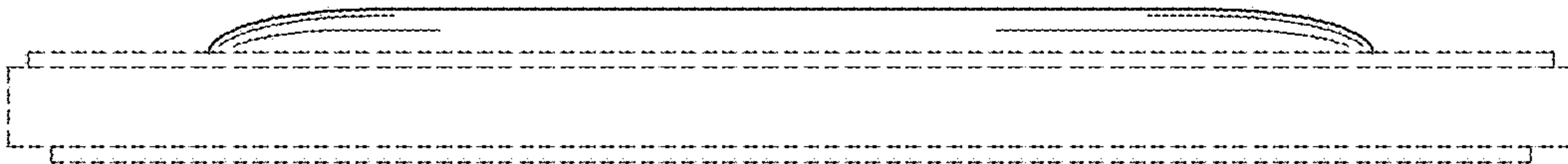


FIG. 19

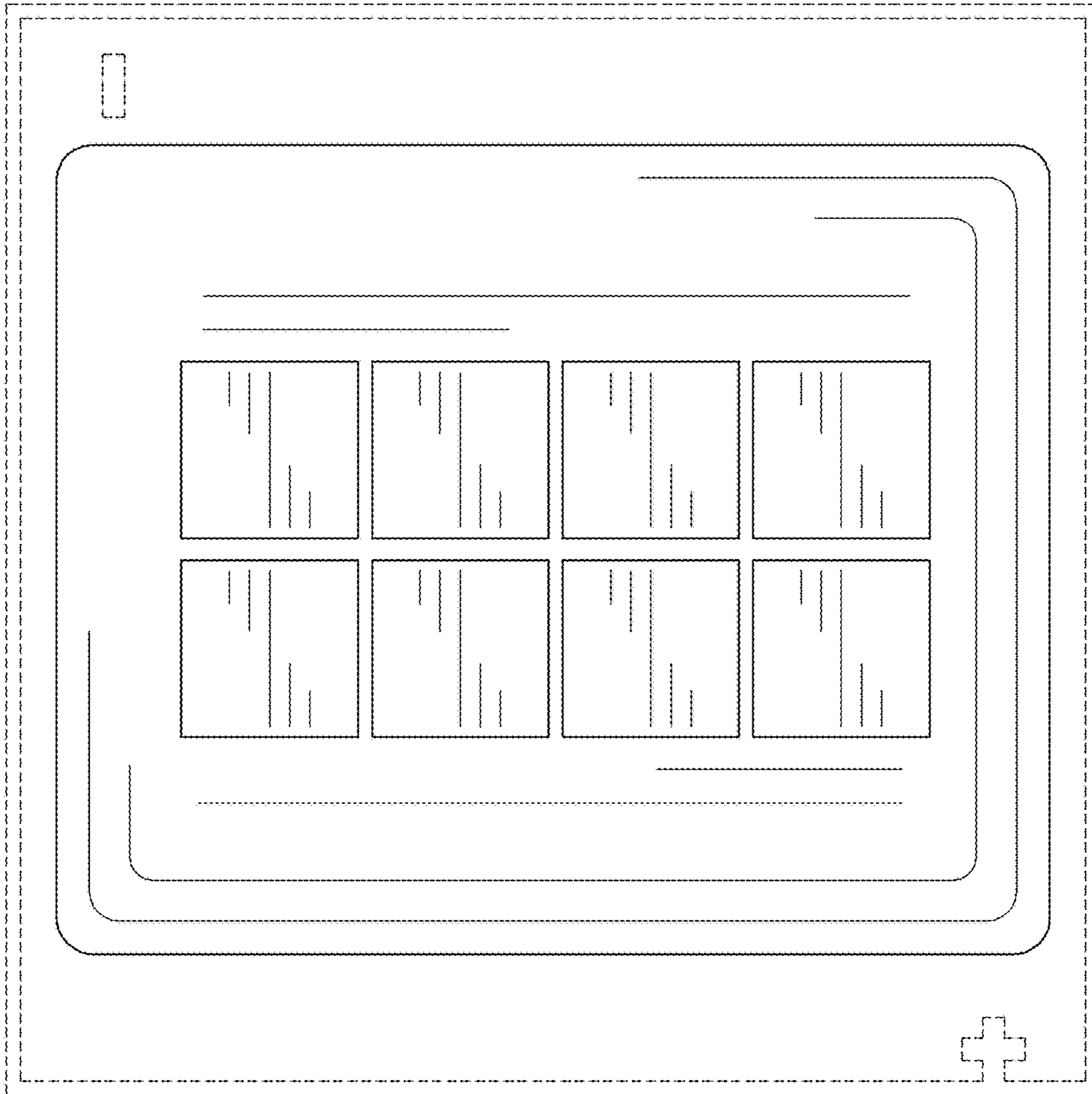


FIG. 20

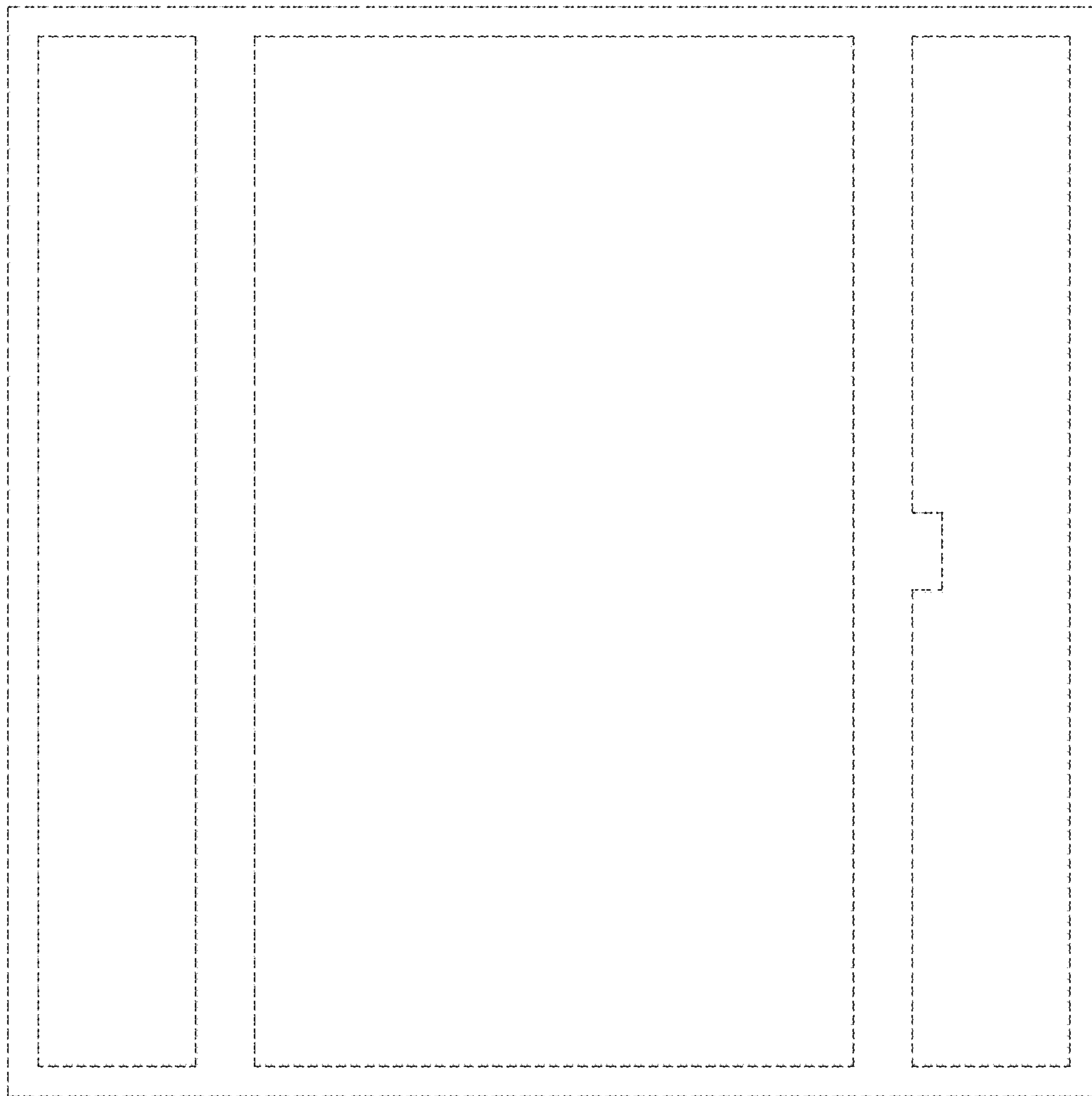


FIG. 21